

**LTM2881 32LD, BGA, 15mm X 11.25mm X 3.42mm (TABLE OF MATERIAL DECLARATION)**

*The LTM2881 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1592	Barium Compounds	7727-43-7	0.00252	1.58
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	13776-74-4,7631-86-9	0.04146	26.04
				Copper Metal	7440-50-8	0.07459	46.85
				Copper Compounds	1328-53-6	0.00002	0.01
				Ecotoxic substances	7440-38-2,7440-28-0	0.00001	0.01
				Gold metal or alloy	7440-57-5	0.00032	0.20
				Nickel	7440-02-0	0.00204	1.28
				Zinc	7440-66-6	0.00008	0.05
				Continuos Filament Fiber Glass	non-disclosure	0.03257	20.46
				Acrylic Resin	non-disclosure	0.00479	3.01
				Epoxy Resin	non-disclosure	0.00005	0.03
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00003	0.02
				Talc;not containing fibers like asbestos	14807-96-9	0.00029	0.18
				Aromatic Carbonyl compounds	non-disclosure	0.00027	0.17
				Cyanoguanidine	461-58-5	0.00001	0.01
				Imidazole system curing reagent	non-disclosure	0.00000	0.00
				Amine compounds	non-disclosure	0.00004	0.02
				Leveling agent and others	non-disclosure	0.00011	0.07
2	Solder Paste	Alloy	0.0064	Sn	7440-31-5	0.00606	95.00
				Sb	7440-36-0	0.00032	5.00
3	Epoxy		0.0056	Di-ester resin	non-disclosure	0.00045	8.00
				Functionalized ester	non-disclosure	0.00045	8.00
				Silver	7440-22-4	0.00469	84.00
4	Passive/Active Components		0.1936	Fe Oxide	1317-61-9	0.02800	14.46
				Mn Oxide	1317-35-7	0.00800	4.13
				Zn Oxide	1314-13-2	0.00400	2.07
				Glass fibers	65997-17-3	0.01800	9.30
				Copper (Cu)	7440-50-8	0.04516	23.33
				Tin (Sn)	7440-31-5	0.01328	6.86
				Nickel (Ni)	7440-02-0	0.00508	2.62
				Antimony (Sb)	7440-36-0	0.00225	1.16
				Adhesive	25068-38-6	0.00300	1.55
				Resins	25053-15-0	0.03020	15.60
				Ceramic (Ba Compounds)	12047-27-7	0.03658	18.89
5	Active Ics	Silicon	0.0046	Silicon	7440-21-3	0.00456	100.00
6	Wire	Gold	0.0012	Au	7440-57-5	0.00118	99.99
7	Encapsulation	Epoxy Resin	0.6855	Fused Silica	60676-86-0	0.52921	77.20
				Epoxy Resin	non-disclosure	0.06101	8.90
				Phenol Resin	non-disclosure	0.06101	8.90
				Crytalline Silica	14808-60-7	0.02057	3.00
				Carbon Black	1333-86-4	0.00343	0.50
				Metal Hydroxide	non-disclosure	0.01028	1.50
7	Solder Ball	Alloy	0.0608	Tin	7440-31-5	0.05837	96.50
				Silver	7440-22-4	0.00213	3.00
				Copper	7440-50-8	0.00030	0.50
Total Package Weight			1.1168				

Note: Composition derived from MSDS and material C of C from Vendors.Component Weight based on assembly of generic parts